

# ISL3084

Data Sheet

# May 2003

### FN5042.3

# 5GHz VCO



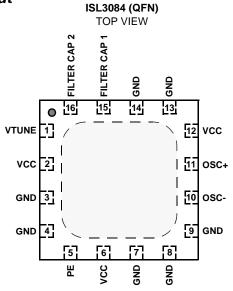
The ISL3084 is a 5GHz SiGe monolithic VCO circuit designed to simplify and reduce the cost and size of miniature wireless transceivers.

A fully integrated VCO requiring no external elements such as inductors and varactors greatly simplifies low cost local oscillator synthesized applications.

Included in this differential design is a low-power standby function and a stable process and temperature biasing operation.

The ISL3084 is housed in a 16 lead QFN package well-suited for PCMCIA and miniPCI board applications.

# Pinout



# **Pin Descriptions**

#### **PIN NUMBER** DESCRIPTION NAME VTUNE Input tuning voltage from loop filter. Sensitivity to external injected noise to KVCO. Careful noise-free 1 lavout recommended. 2, 6, 12 VCC Supply pins. Requires high quality capacitor RF decoupling. Phase noise behavior proportional to supply pushing specifications. Use good quality, low-frequency decoupling/filtering techniques. ΡE 5 Power enable control pin: VCO enabled high. 10 OSC-Differential VCO output. Terminate into $100\Omega$ differential impedance. Terminate one end into $50\Omega$ when single end output with equivalent loss of power. 11 OSC+ FILTER CAP1 15 Use high quality .68µF filter capacitor to ground. **FILTER CAP2** 16 Use high quality .68µF filter capacitor to VCC. 3, 4, 7, 8, 9, 13, 14 GND Ground

Floating paddle. Grounding is recommended.

ned to	Frequency 4.9GHz typical
and size	<ul> <li>Fully Integrated/No External Varactors or Resonators</li></ul>
ivers.	Required

• Isolation Output Buffer/Reduced Load Pulling

- Differential Design/Reduced Spurs
- Digitally Controlled Power Down Mode
- QFN Package:

Features

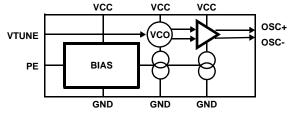
- Compliant to JEDEC PUB95 MO-220 QFN - Quad Flat No Leads - Package Outline

- Near Chip Scale Package footprint, which improves PCB efficiency and has a thinner profile

# Applications

- Systems Targeting IEEE802.11b, 11Mbps Standard
- Only required VCO function for Intersil PRISM®3 chip set
- WLAN Applications.
- PCMCIA Wireless Transceivers
- TDMA Packet Protocol Radios

# Simplified Block Diagram



# Ordering Information

PART NUMBER	TEMP. RANGE ( <sup>o</sup> C)	PACKAGE	PKG. NO.
ISL3084IR	-40 to 85	16 Ld QFN	L16.4x4
ISL3084IR-TK	-40 to 85	Tape and Reel	

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CAUTION: These devices are sensitive to electrostatic discharge; follow proper IC Handling Procedures.

N/A

1

Paddle

#### **Absolute Maximum Ratings**

Supply Voltage	δV
Voltage on Any Other Pin	3V
V <sub>CC</sub> to V <sub>CC</sub> Decouple	3V
Any GND to GND	3V

### **Operating Conditions**

Temperature Range	40 <sup>o</sup> to 85 <sup>o</sup> C
Supply Voltage Range	2.7V to 3.3V

#### **Thermal Information**

Thermal Resistance (Typical, Note 1)	θ <sub>JA</sub> ( <sup>o</sup> C/W)
QFN Package	47
Junction Temperature (Plastic Package)	
Maximum Storage Temperature Range	5 <sup>o</sup> C to 150 <sup>o</sup> C
For recommended soldering conditions see Tech Brief	TB389.

CAUTION: Stresses above those listed in "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress only rating and operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.

#### NOTE:

1. θ<sub>JA</sub> is measured in free air with the component mounted on a high effective thermal conductivity test board with "direct attach" features. See Tech Brief TB379.

#### **General DC Electrical Specifications** TA = 25°C

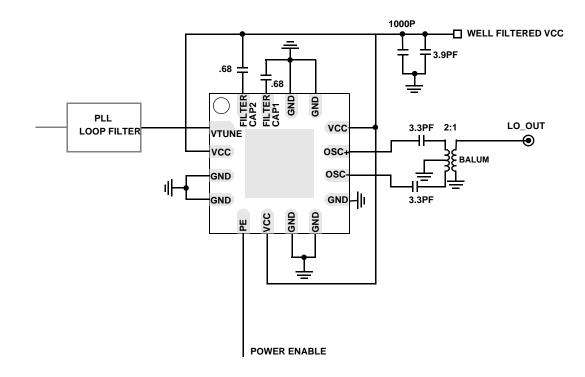
PARAMETER	MIN	ТҮР	MAX	UNITS
Supply Voltage	2.7	-	3.0	V
Supply Current @ 3.3V	-	-	20	mA
Power Down Supply Current	-	-	100	μΑ
Power Up Time, Filtering dependent	-	50	-	μS
Power Down Time	-	-	1	μS
CMOS Low-Level Input Voltage	-	-	0.3*VCC	V
CMOS High-Level Input Voltage	0.7*V <sub>CC</sub>	-	-	V
CMOS High- or Low-Level Input Current	-10	-	10	μΑ

#### AC Electrical Specifications VCC = 2.7 to 3.3V, Vtune operation from 0.5 to 2.2V, TA = 25°C

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNITS
RF Frequency Ranges	Vtune = 0.5V	-	4.67	4.79	GHz
	Vtune = 1.35V	-	4.92	-	GHz
	Vtune = 2.2V	5.0	5.19	-	GHz
Tuning Voltage Temperature Coefficient	Vtune = 1.35V, -40 to 85 <sup>o</sup> C	-	40	-	MHz
Tuning Pin Input Leakage	Vtune = 2.0V	-	-	2	μΑ
VCO Gain	Vtune = 1.35V	250	300	350	MHz/V
VCO Gain Temperature Coefficient	Vtune = 1.35V, -40 to 85 <sup>o</sup> C	-	20	-	MHz/V
Phase Noise	Offset 10kHz	65	70	-	dBc/Hz
	Offset 100kHz	-	95	-	dBc/Hz
Phase Noise Temperature Coefficient	Offset @ 10kHz, 0 to 85 <sup>0</sup> C	-	1	4	dB
Integrated Phase Noise @ 5GHz.	10kHz to 1MHz	-	1.6		deg_rms
Output Power	Differential into $100\Omega$	-9	-4	-	dBm
Supply Pushing	VCC = 2.7V–3.3V, across Vtune range	-3	+2	+10	MHz
Load Pulling	VSWR = 2:1		1.8		MHz
Output VSWR	2:1 BALUM	-	1.3:1		-
			1	1	1

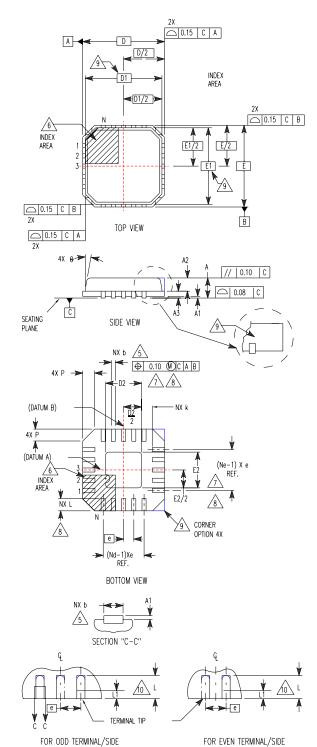
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# Typical Application



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3



# Quad Flat No-Lead Plastic Package (QFN) Micro Lead Frame Plastic Package (MLFP)

#### L16.4x4

16 LEAD QUAD FLAT NO-LEAD PLASTIC PACKAGE (COMPLIANT TO JEDEC MO-220-VGGC ISSUE C)

IN 80 - - 23	NOMINAL 0.90 - - 0.20 REF	MAX 1.00 0.05 1.00	NOTES -
-	-	0.05	-
-	-		-
	-	1.00	
23			9
23	0.20 KEF		9
	0.28	0.38	5, 8
4.00 BSC			-
3.75 BSC			9
95	2.10	2.25	7, 8
4.00 BSC			-
	3.75 BSC		9
95	2.10	2.25	7, 8
	0.65 BSC		-
25	-	-	-
35	0.60	0.75	8
-	-	0.15	10
	16		2
	4		3
	4		3
-	-	0.60	9
	-	12	9
-	-		4 0.60

#### NOTES:

- 1. Dimensioning and tolerancing conform to ASME Y14.5-1994.
- 2. N is the number of terminals.
- 3. Nd and Ne refer to the number of terminals on each D and E.
- 4. All dimensions are in millimeters. Angles are in degrees.
- 5. Dimension b applies to the metallized terminal and is measured between 0.15mm and 0.30mm from the terminal tip.
- The configuration of the pin #1 identifier is optional, but must be located within the zone indicated. The pin #1 identifier may be either a mold or mark feature.
- Dimensions D2 and E2 are for the exposed pads which provide improved electrical and thermal performance.
- 8. Nominal dimensions are provided to assist with PCB Land Pattern Design efforts, see Intersil Technical Brief TB389.
- 9. Features and dimensions A2, A3, D1, E1, P & 0 are present when Anvil singulation method is used and not present for saw singulation.
- Depending on the method of lead termination at the edge of the package, a maximum 0.15mm pull back (L1) maybe present. L minus L1 to be equal to or greater than 0.3mm.

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